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Part Number: **0737700100**
Status: **Active**
Overview: HDM® Backplane Connector System
Description: HDM® Board-to-Board Stacking Header, High Rise Vertical, SMC, Closed End Option, 72 Circuits

Documents:

[3D Model](#) [Product Specification PS-73780-999 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

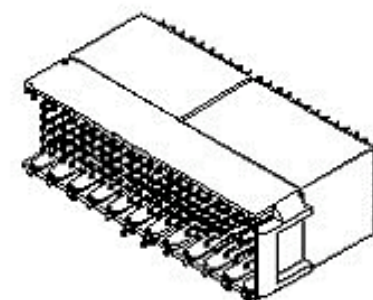
CSA LR19980
 UL E29179

General

Product Family Backplane Connectors
 Series 73770
 Application Backplane, Mezzanine
 Component Type PCB Header
 MolexKits Yes
 Overview HDM® Backplane Connector System
 Product Name HDM®
 UPC 800755029000

Physical

Circuits (Loaded) 72
 Circuits (maximum) 72
 Color - Resin Black
 Durability (mating cycles max) 200
 First Mate / Last Break No
 Flammability 94V-0
 Guide to Mating Part No
 Keying to Mating Part None
 Material - Metal Phosphor Bronze
 Material - Plating Mating Gold
 Material - Plating Termination Tin-Lead
 Material - Resin High Temperature Thermoplastic
 Net Weight 13.179/g
 Number of Columns 12
 Number of Pairs Open Pin Field
 Number of Rows 6
 Orientation Vertical
 PC Tail Length 3.50mm
 PCB Locator No
 PCB Retention None
 PCB Thickness - Recommended 1.40mm
 Packaging Type Tube
 Pitch - Mating Interface 2.00mm
 Pitch - Termination Interface 2.00mm
 Plating min - Mating 0.762µm
 Plating min - Termination 0.381µm
 Polarized to PCB No
 Stackable Yes
 Surface Mount Compatible (SMC) Yes
 Temperature Range - Operating -55°C to +105°C
 Termination Interface: Style Through Hole - Compliant Pin



Series image - Reference only

EU ELV

Not Relevant

EU RoHS

Compliant

REACH SVHC

Contains SVHC(2014 December 17): No

Halogen-Free

Status

Low-Halogen

Need more information on product environmental compliance?

Email productcompliance@molex.com
 Please visit the [Contact Us](#) section for any non-product compliance questions.

China ROHS

ELV

Green Image

Not Relevant

Search Parts in this Series

73770 Series

Mates With

73632 HDM PLUS® Board-to-Board Daughtercard Receptacle. 73780 HDM® Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description	Product #
Extraction Tool	<u>0621001000</u>
Backplane Insertion	<u>0621001400</u>
Signal Contact Tool	

Electrical

Current - Maximum per Contact	1.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	72
Voltage - Maximum	250V AC

Solder Process Data

Lead-free Process Capability	N/A
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Material Info**Reference - Drawing Numbers**

Product Specification	PS-73780-999
Sales Drawing	SD-73770-001

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